●USP-10B Power Dissipation

Power dissipation data for the USP-10B is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm×40mm（1600mm^2 in one side）

1st Inner Metal Layer about 50%

2nd Inner Metal Layer does not exist

3rd Inner Metal Layer does not exist

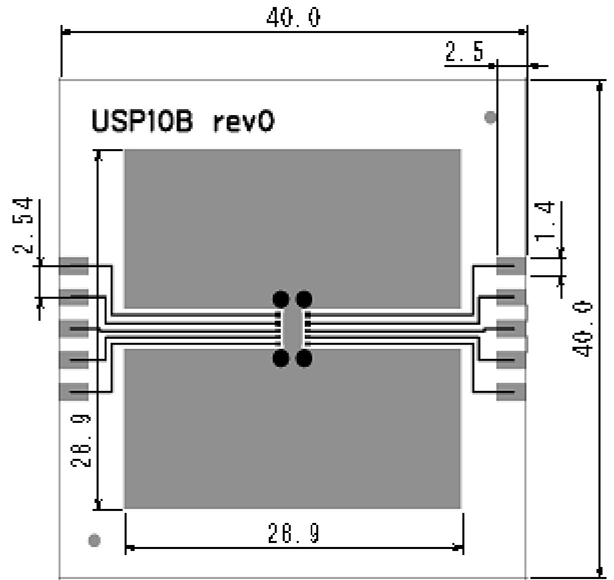
4th Inner Metal Layer about 50%

Each heat sink back metal is connected to the Inner layers respectively.

Material : Glass Epoxy（FR-4）

Thickness : 1.6mm

Through-hole : 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
85	400